

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPG20N04S4-09	**Issued**	27. April 2022
MA#	MA005739324		
Package	PG-TDSON-8-4	**Weight***	96.99 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.237	1.28	1.28	12754	12754
chip_2	inorganic material	silicon	7440-21-3	1.237	1.28	1.28	12754	12754
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		138	
	non noble metal	iron	7439-89-6	0.044	0.05		458	
	non noble metal	copper	7440-50-8	44.409	45.78	45.84	457890	458486
wire	non noble metal	aluminium	7429-90-5	0.777	0.80	0.80	8014	8014
encapsulation	organic material	carbon black	1333-86-4	0.090	0.09		924	
	plastics	epoxy resin	-	6.361	6.56		65588	
	inorganic material	silicondioxide	60676-86-0	38.346	39.54	46.19	395376	461888
leadfinish	non noble metal	tin	7440-31-5	1.308	1.35	1.35	13483	13483
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.048	0.05	0.05	495	496
solder	non noble metal	tin	7440-31-5	0.057	0.06		592	
	noble metal	silver	7440-22-4	0.072	0.07		740	
	non noble metal	lead	7439-92-1	2.741	2.83	2.96	28264	29596
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.245	0.25	0.25	2525	2529
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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